

384-OUTPUT TFT-LCD SOURCE DRIVER (COMPATIBLE WITH 64-GRAY SCALES)

DESCRIPTION

The μ PD16716 is a source driver for TFT-LCDs capable of dealing with displays with 64-gray scales. Data input is based on digital input configured as 6 bits by 6 dots (2 pixels), which can realize a full-color display of 260,000 colors by output of 64 values γ -corrected by an internal D/A converter and 5-by-2 external power modules. Because the output dynamic range is as large as $V_{SS2} + 0.1$ V to $V_{DD2} - 0.1$ V, level inversion operation of the LCD's common electrode is rendered unnecessary. Also, to be able to deal with dot-line inversion, n-line inversion and column line inversion when mounted on a single side, this source driver is equipped with a built-in 6-bit D/A converter circuit whose odd output pins and even output pins respectively output gray scale voltages of differing polarity. Assuring a maximum clock frequency of 70 MHz when driving at 3.0 V, 45 MHz when driving at 2.5 V, this driver is applicable to XGA/SXGA-standard TFT-LCD panels.

FEATURES

- CMOS level input (2.5 to 3.6 V)
- 384 Outputs
- Input of 6 bits (gray scale data) by 6 dots
- Capable of outputting 64 values by means of 5-by-2 external power modules (10 units) and a D/A converter (R-DAC)
- Logic power supply voltage (V_{DD1}) : 2.5 to 3.6 V
- Driver power supply voltage (V_{DD2}) : 15.0 V \pm 0.5 V
- Output dynamic range $V_{SS2} + 0.1$ V to $V_{DD2} - 0.1$ V
- High-speed data transfer: $f_{CLK} = 70$ MHz (internal data transfer speed when operating at $V_{DD1} = 3.0$ V),
45 MHz (internal data transfer speed when operating at $V_{DD1} = 2.5$ V)
- Apply for dot-line inversion, n-line inversion and column line inversion
- Output Voltage polarity inversion function (POL)
- Display data inversion function (capable of controlling by each input port) (POL21, POL22)
- Low power control function (LPC)

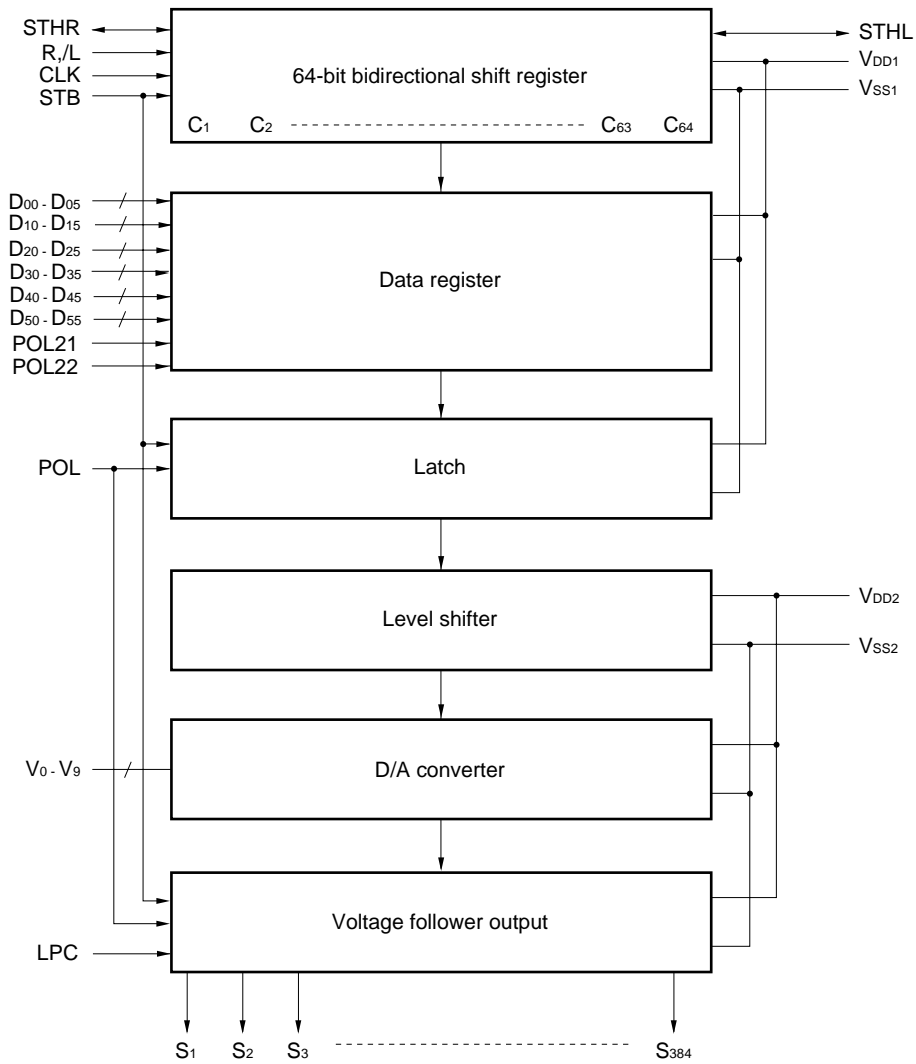
ORDERING INFORMATION

Part Number	Package
μ PD16716N-xxx	TCP (TAB package)

Remark The TCP's external shape is customized. To order your TCP's external shape, please contact one of our sales representatives.

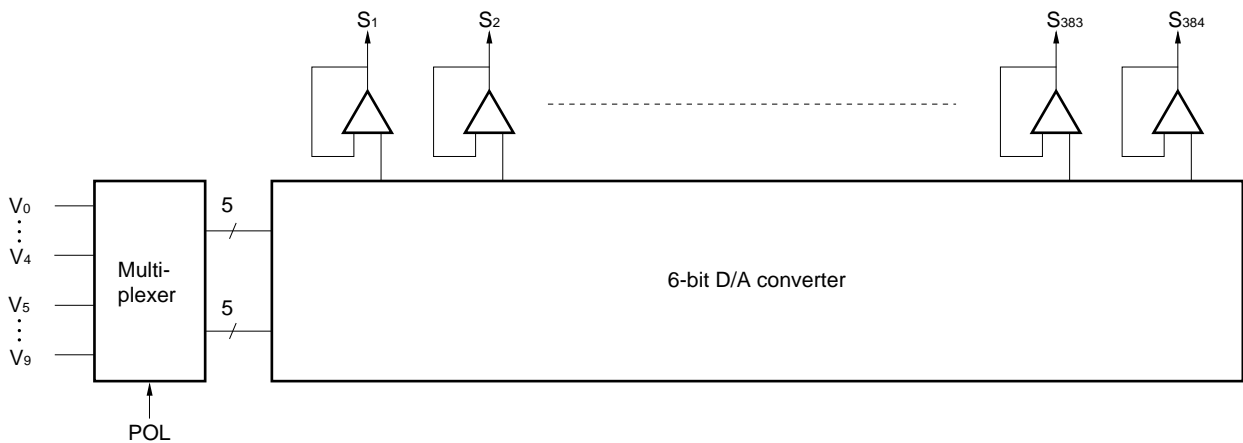
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1. BLOCK DIAGRAM

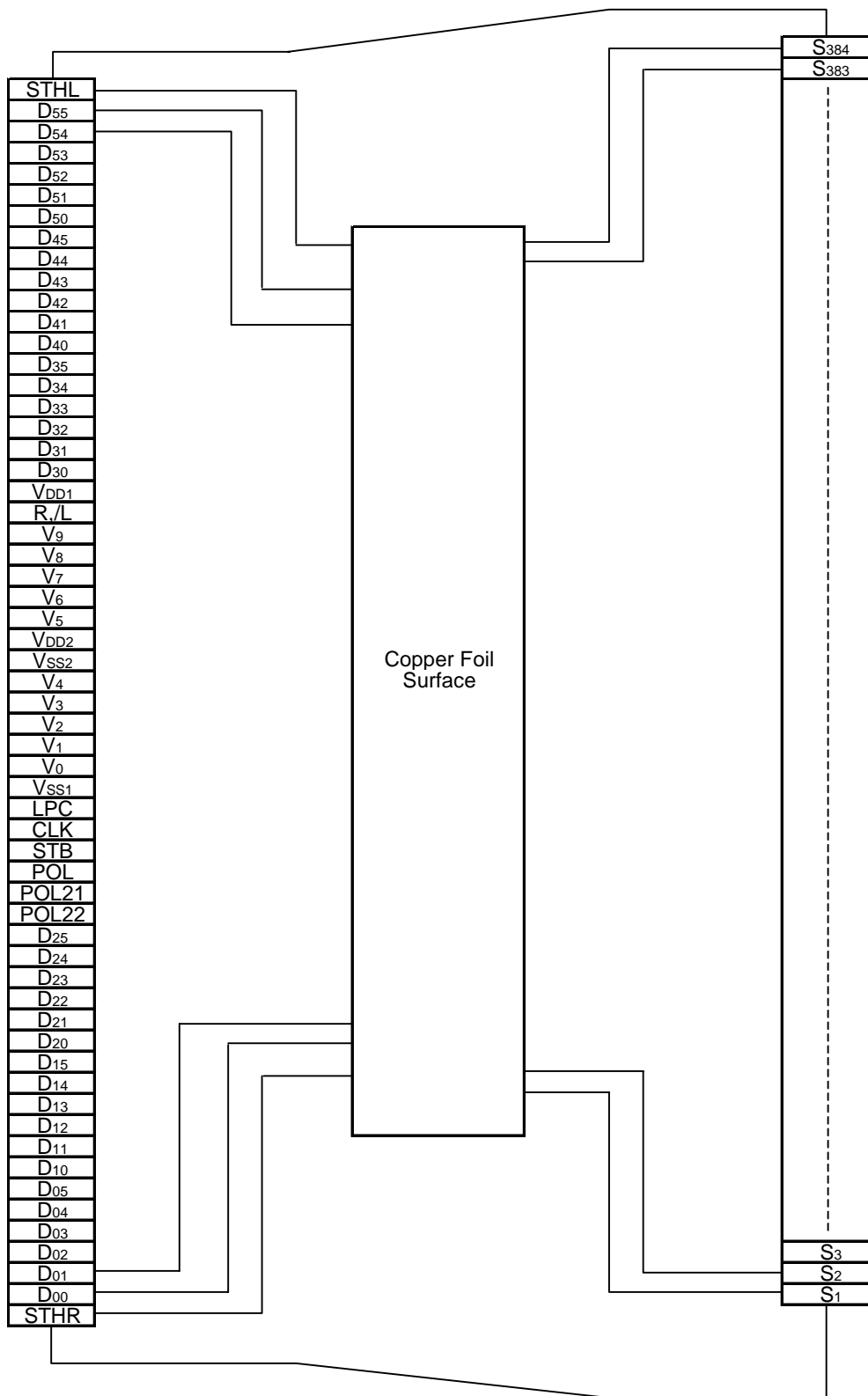


Remark /xxx indicates active low signal.

2. RELATIONSHIP BETWEEN OUTPUT CIRCUIT AND D/A CONVERTER



3. PIN CONFIGURATION (μ PD16716N-xxx) (Copper Foil Surface, Face-up)



Remark This figure does not specify the TCP package.

4. PIN FUNCTIONS

(1/2)

Pin Symbol	Pin Name	I/O	Description
S ₁ to S ₃₈₄	Driver	O	The D/A converted 64-gray-scale analog voltage is output.
D ₀₀ to D ₀₅	Display data	I	The display data is input with a width of 36 bits, viz., the gray scale data (6 bits) by 6 dots (2 pixels). D _{x0} : LSB, D _{x5} : MSB
D ₁₀ to D ₁₅			
D ₂₀ to D ₂₅			
D ₃₀ to D ₃₅			
D ₄₀ to D ₄₅			
D ₅₀ to D ₅₅			
R,/L	Shift direction control	I	Refers to the shift direction control. The shift directions of the shift registers are as follows. R,/L = H : STHR input, S ₁ → S ₃₈₄ , STHL output R,/L = L : STHL input, S ₃₈₄ → S ₁ , STHR output
★ STHR	Right shift start pulse	I/O	These refer to the start pulse I/O pins when driver ICs are connected in cascade. Loading of display data starts when H is read at the rising edge of CLK. R,/L = H (right shift): STHR input, STHL output R,/L = L (left shift): STHL input, STHR output A high level should be input as the pulse of one cycle of the clock signal. If the start pulse input is more than 2CLK, the first 1CLK of the high-level input is valid.
★ STHL	Left shift start pulse	I/O	
★ CLK	Shift clock	I	Refers to the shift register's shift clock input. The display data is loaded into the data register at the rising edge. At the rising edge of the 64th clock after the start pulse input, the start pulse output reaches the high level, thus becoming the start pulse of the next-level driver. If 66-clock pulses are input after input of the start pulse, input of display data is halted automatically. The contents of the shift register are cleared at the STB's rising edge.
STB	Latch	I	The contents of the data register are transferred to the latch circuit at the rising edge. And, at the falling edge, the gray scale voltage is supplied to the driver. It is necessary to ensure input of one pulse per horizontal period.
POL	Polarity	I	POL = L : The S _{2n-1} output uses V ₀ to V ₄ as the reference supply. The S _{2n} output uses V ₅ to V ₉ as the reference supply. POL = H : The S _{2n-1} output uses V ₅ to V ₉ as the reference supply. The S _{2n} output uses V ₀ to V ₄ as the reference supply. S _{2n-1} indicates the odd output: and S _{2n} indicates the even output. Input of the POL signal is allowed the setup time (t _{POL-STB}) with respect to STB's rising edge.
★ POL21, POL22	Data inversion	I	Data inversion can invert when display data is loaded. POL21: Invert/not invert of display data D ₀₀ to D ₀₅ , D ₁₀ to D ₁₅ , D ₂₀ to D ₂₅ . POL22: Invert/not invert of display data D ₃₀ to D ₃₅ , D ₄₀ to D ₄₅ , D ₅₀ to D ₅₅ . POL21, POL22 = H : Display data is inverted. POL21, POL22 = L : Display data is not inverted.
LPC	Low power control	I	The current consumption is lowered by controlling the constant current source of the output amplifier. This pin is pulled up to the V _{DD1} power supply inside the IC. In low power mode (LPC = L), the static current consumption of V _{DD2} reduced to about 2/3 of the normal current consumption. LPC = H or Open : Normal power mode LPC = L : Low power mode

(2/2)

Pin Symbol	Pin Name	I/O	Description
V ₀ to V ₉	γ-corrected power supplies	–	Input the γ-corrected power supplies from outside by using operational amplifier. Make sure to maintain the following relationships. During the gray scale voltage output, be sure to keep the gray scale level power supply at a constant level. $V_{DD2} - 0.1\text{ V} \geq V_0 > V_1 > V_2 > V_3 > V_4 \geq 0.5 V_{DD2} \geq V_5 > V_6 > V_7 > V_8 > V_9 \geq V_{SS2} + 0.1\text{ V}$
V _{DD1}	Logic power supply	–	2.5 V to 3.6 V
V _{DD2}	Driver power supply	–	15.0 V ± 0.5 V
V _{SS1}	Logic ground	–	Grounding
V _{SS2}	Driver ground	–	Grounding

- Cautions**
1. The power start sequence must be V_{DD1}, logic input, and V_{DD2} & V₀ to V₉ in that order. Reverse this sequence to shut down. (Simultaneous power application to V_{DD2} and V₀ to V₉ is possible.)
 2. To stabilize the supply voltage, please be sure to insert a 0.1 μF bypass capacitor between V_{DD1}-V_{SS1} and V_{DD2}-V_{SS2}. Furthermore, for increased precision of the D/A converter, insertion of a bypass capacitor of about 0.01 μF is also advised between the γ-corrected power supply terminals (V₀, V₁, V₂, ..., V₉) and V_{SS2}.

5. RELATIONSHIP BETWEEN INPUT DATA AND OUTPUT VOLTAGE VALUE

This product incorporates a 6-bit D/A converter whose odd output pins and even output pins output respectively gray scale voltages of differing polarity with respect to the LCD's counter electrode (common electrode) voltage. The D/A converter consists of ladder resistors and switches.

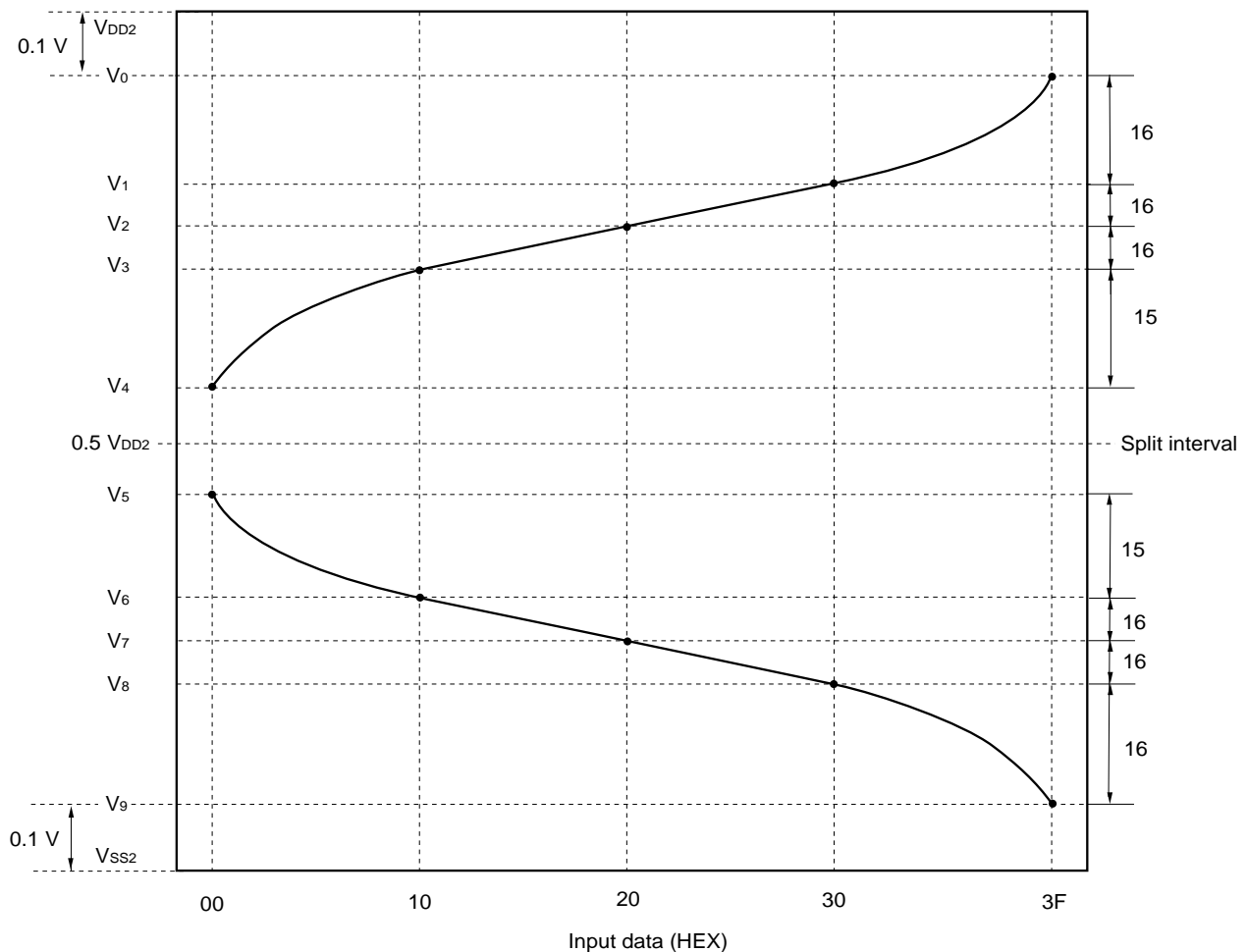
The ladder resistors (r0 to r62) are designed so that the ratio of LCD panel γ -compensated voltages to V_0' to V_{63}' and V_0'' to V_{63}'' is almost equivalent. For the 2 sets of five γ -compensated power supplies, V_0 to V_4 and V_5 to V_9 , respectively, input gray scale voltages of the same polarity with respect to the common voltage. When fine-gray scale voltage precision is not necessary, there is no need to connect a voltage follower circuit to the γ -compensated power supplies V_1 to V_3 and V_6 to V_8 .

Figure 5-1 shows the relationship between the driving voltages such as liquid-crystal driving voltages V_{DD2} and V_{SS2} , common electrode potential V_{COM} , and γ -corrected voltages V_0 to V_9 and the input data. Be sure to maintain the voltage relationships as follows:

$$V_{DD2} - 0.1 \text{ V} \geq V_0 > V_1 > V_2 > V_3 > V_4 \geq 0.5 V_{DD2} \geq V_5 > V_6 > V_7 > V_8 > V_9 \geq V_{SS2} + 0.1 \text{ V}.$$

Figures 5-2 and 5-3 show the relationship between input data and output voltage. This driver IC is designed for only single-sided mounting

Figure 5-1. Relationship between Input Data and γ -corrected Power Supply



6. RELATIONSHIP BETWEEN INPUT DATA AND OUTPUT PIN

Data format: 6 bits × 2 RGBs (6 dots)

Input width : 36 bits (2-pixel data)

R,/L = H (Right shift)

Output	S ₁	S ₂	S ₃	S ₄	...	S ₃₈₃	S ₃₈₄
Data	D ₀₀ to D ₀₅	D ₁₀ to D ₁₅	D ₂₀ to D ₂₅	D ₃₀ to D ₃₅	...	D ₄₀ to D ₄₅	D ₅₀ to D ₅₅

R,/L = L (Left shift)

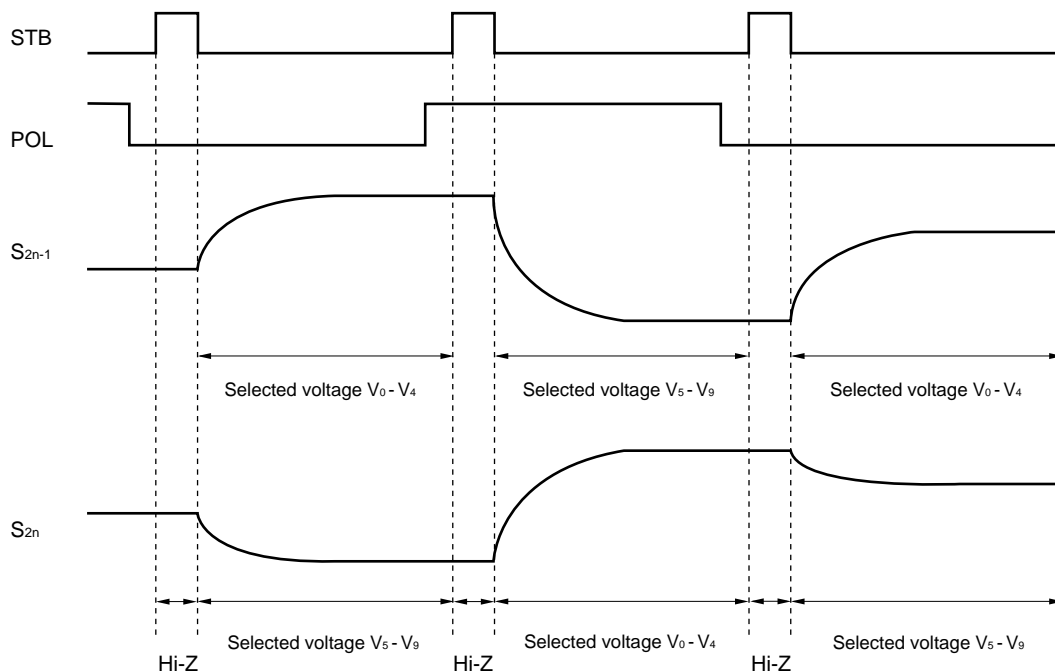
Output	S ₁	S ₂	S ₃	S ₄	...	S ₃₈₃	S ₃₈₄
Data	D ₀₀ to D ₀₅	D ₁₀ to D ₁₅	D ₂₀ to D ₂₅	D ₃₀ to D ₃₅	...	D ₄₀ to D ₄₅	D ₅₀ to D ₅₅

POL	S _{2n-1} Note	S _{2n} Note
L	V ₀ to V ₄	V ₅ to V ₉
H	V ₅ to V ₉	V ₀ to V ₄

Note S_{2n-1} (Odd output), S_{2n} (Even output)

7. RELATIONSHIP BETWEEN STB, POL, AND OUTPUT WAVEFORM

The output voltage is written to the LCD panel synchronized with the STB falling edge.



8. RELATIONSHIP BETWEEN STB, CLK, AND OUTPUT WAVEFORM

The output voltage is written to the LCD panel synchronized with the STB falling edge.

Figure 8-1. Output Circuit Block Diagram

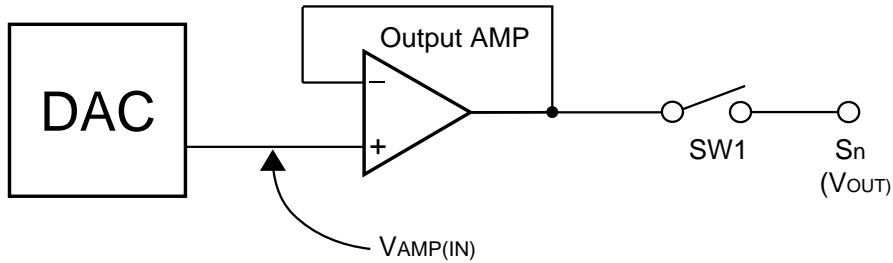
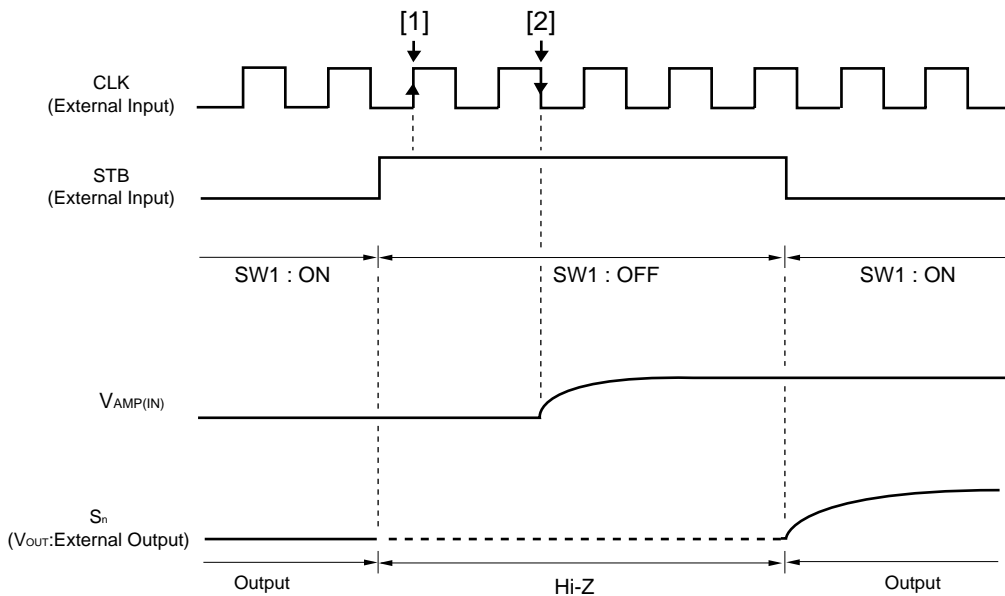


Figure 8-2. Output Circuit Timing Waveform



- Remarks 1.** STB = L : SW1 = ON
 STB = H : SW1 = OFF
- 2.** STB = "H" is acknowledged at timing [1].
- 3.** The display data latch is completed at timing [2] and the input voltage ($V_{AMP(IN)}$: gray-scale level voltage) of the output amplifier changes.

9. ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings (T_A = +25°C, V_{SS1} = V_{SS2} = 0 V)

Parameter	Symbol	Rating	Unit
Logic Part Supply Voltage	V _{DD1}	-0.5 to +4.0	V
Driver Part Supply Voltage	V _{DD2}	-0.5 to +17.0	V
Logic Part Input Voltage	V _{I1}	-0.5 to V _{DD1} + 0.5	V
Driver Part Input Voltage	V _{I2}	-0.5 to V _{DD2} + 0.5	V
Logic Part Output Voltage	V _{O1}	-0.5 to V _{DD1} + 0.5	V
Driver Part Output Voltage	V _{O2}	-0.5 to V _{DD2} + 0.5	V
Operating Ambient Temperature	T _A	-10 to +75	°C
Storage Temperature	T _{stg}	-55 to +125	°C

Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.

Recommended Operating Range (T_A = -10 to +75°C, V_{SS1} = V_{SS2} = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Logic Part Supply Voltage	V _{DD1}		2.5		3.6	V
Driver Part Supply Voltage	V _{DD2}		14.5	15.0	15.5	V
High-Level Input Voltage	V _{IH}		0.7 V _{DD1}		V _{DD1}	V
Low-Level Input Voltage	V _{IL}		0		0.3 V _{DD1}	V
γ-Corrected Voltage	V ₀ to V ₉		V _{SS2} + 0.1		V _{DD2} - 0.1	V
Driver Part Output Voltage	V _O		V _{SS2} + 0.1		V _{DD2} - 0.1	V
Clock Frequency	f _{CLK}	V _{DD1} = 3.0 V			70	MHz
		V _{DD1} = 2.5 V			45	MHz

★ **Electrical Characteristics** ($T_A = -10$ to $+75^\circ\text{C}$, $V_{DD1} = 2.5$ to 3.6 V, $V_{DD2} = 15.0$ V \pm 0.5 V, $V_{SS1} = V_{SS2} = 0$ V, Unless otherwise specified, power mode = normal, Bcont = open)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit	
Input Leak Current	I_{IL}				± 1.0	μA	
High-Level Output Voltage	V_{OH}	STHR (STHL), $I_{OH} = 0$ mA	$V_{DD1} - 0.1$			V	
Low-Level Output Voltage	V_{OL}	STHR (STHL), $I_{OL} = 0$ mA			0.1	V	
γ -Corrected Supply Current	I_γ	$V_{DD2} = 15.0$ V V_0 to $V_4 = V_5$ to $V_9 = 7.5$ V V_0 pin, V_5 pin	200		800	μA	
		V_4 pin, V_9 pin	-800		-200	μA	
Driver Output Current	I_{VOH}	$V_X = 14.0$ V, $V_{OUT} = 13.5$ V		-75	-30	μA	
	I_{VOL}	$V_X = 1.0$ V, $V_{OUT} = 1.5$ V	30	90		μA	
Output Voltage Deviation	ΔV_O	$T_A = +25^\circ\text{C}$, $V_{OUT} = 3.0$ V, 7.5 V, 12.0 V		± 10	± 20	mV	
Output swing difference deviation	ΔV_{P-P1}	$V_{DD1} = 3.3$ V, $T_A = +25^\circ\text{C}$	$V_{OUT} = 7.0$ to 8.0 V		± 5	± 10	mV
	ΔV_{P-P2}	$V_{DD2} = 15.0$ V, $T_A = +25^\circ\text{C}$	$V_{OUT} = 1.6$ to 12.8 V		± 7	± 13	mV
	ΔV_{P-P3}	$T_A = +25^\circ\text{C}$	$V_{OUT} = 1.0$ to 14.0 V		± 10	± 20	mV
Logic Part Dynamic Current Consumption	I_{DD1}	V_{DD1}		5	12	mA	
Driver Part Dynamic Current Consumption	I_{DD2}	V_{DD2} , with no load		8	16	mA	

Cautions 1. $f_{STB} = 64$ kHz, $f_{CLK} = 54$ MHz.

2. The TYP. values refer to an all black or all white input pattern. The MAX. value refers to the measured values in the dot checkerboard input pattern.

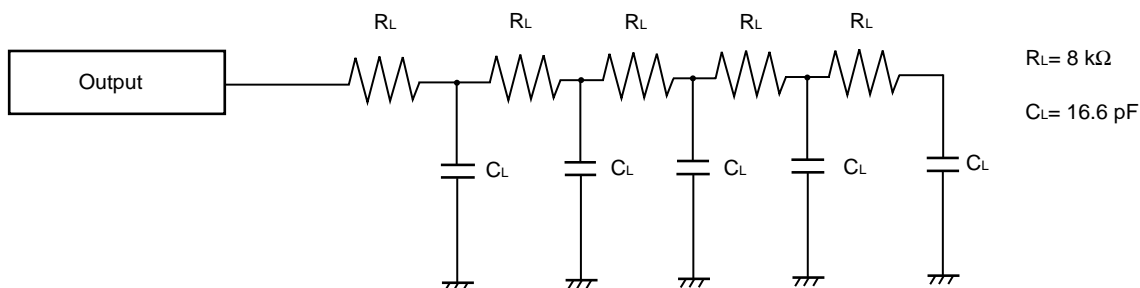
3. Refers to the current consumption per driver when cascades are connected under the assumption of XGA single-sided mounting (8 units).

★ **Switching Characteristics** ($T_A = -10$ to $+75^\circ\text{C}$, $V_{DD1} = 2.5$ to 3.6 V, $V_{DD2} = 15.0$ V \pm 0.5 V, $V_{SS1} = V_{SS2} = 0$ V ,
 Unless otherwise specified, power mode = normal, Bcont = open)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Start Pulse Delay Time	t_{PLH1}	$C_L = 15$ pF			12	ns
Driver Output Delay Time	t_{PLH2}	$C_L = 83$ pF, $R_L = 40$ kΩ			6	μs
	t_{PLH3} Note				12	μs
	t_{PHL2}				7	μs
	t_{PHL3} Note				12	μs
Input Capacitance	C_{i1}	STHR (STHL) excluded, $T_A = +25^\circ\text{C}$		5	10	pF
	C_{i2}	STHR (STHL), $T_A = +25^\circ\text{C}$		10	15	pF

Note t_{PLH3}/t_{PHL3} are specified as the time it takes to reach the target voltage $\pm 2\%$.

<Measurement Condition>



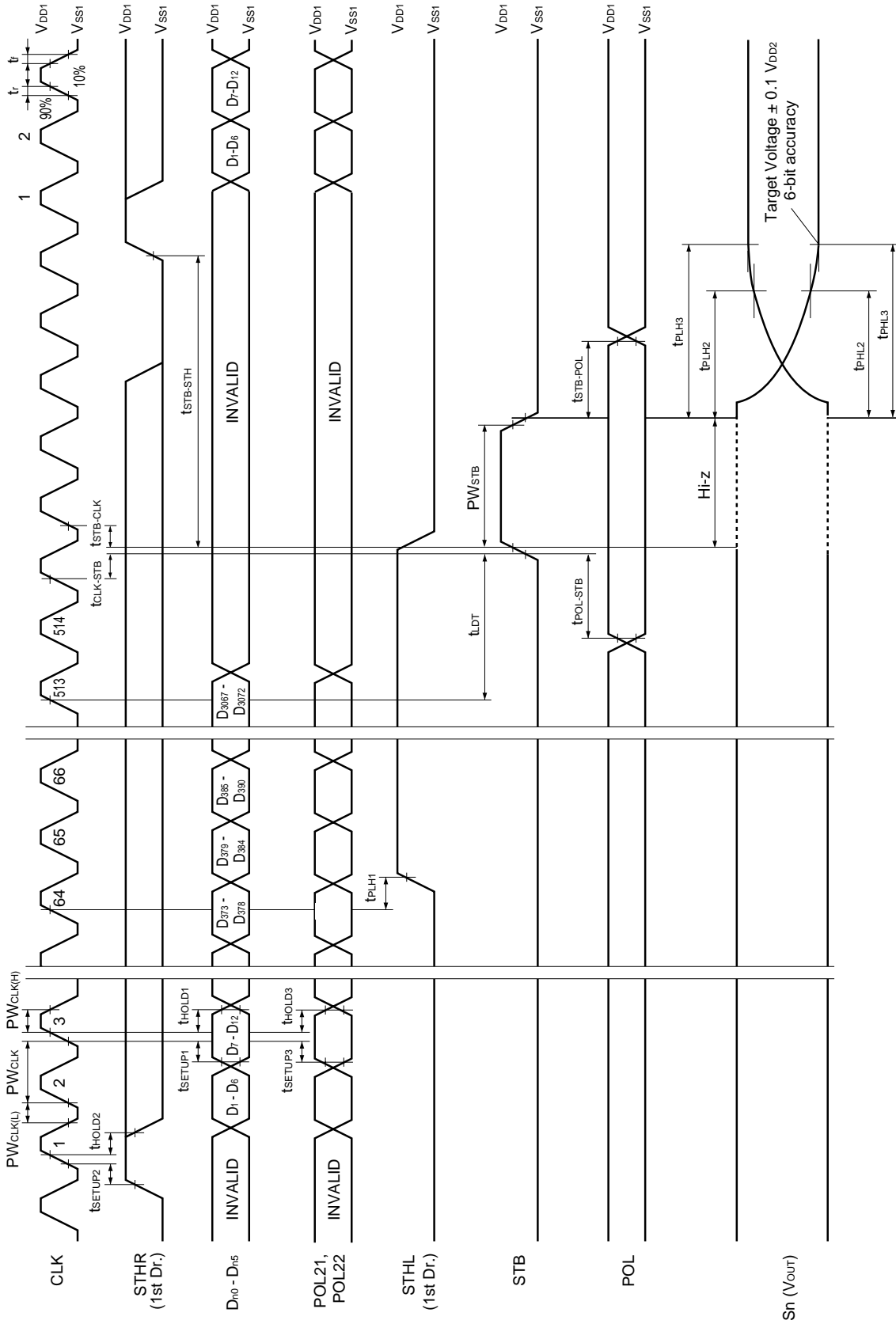
Timing Requirement ($T_A = -10$ to $+75^\circ\text{C}$, $V_{DD1} = 2.5$ to 3.6 V, $V_{SS1} = 0$ V, $t_r = t_f = 5.0$ ns)

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Clock Pulse Width	PW _{CLK}	$V_{DD1} = 3.3 \text{ V} \pm 0.3 \text{ V}$	14			ns
		$V_{DD1} = 2.5$ to 3.0 V	22			ns
Clock Pulse High Period	PW _{CLK(H)}		4			ns
Clock Pulse Low Period	PW _{CLK(L)}		4			ns
Data Setup Time	t _{SETUP1}		2			ns
Data Hold Time	t _{HOLD1}		2			ns
Start Pulse Setup Time	t _{SETUP2}		2			ns
Start Pulse Hold Time	t _{HOLD2}		2			ns
POL21, POL22 Setup Time	t _{SETUP3}		2			ns
POL21, POL22 Hold Time	t _{HOLD3}		2			ns
STB Pulse Width	PW _{STB}		1.5			μs
Last Data Timing	t _{LDT}		2			CLK
CLK-STB Time	t _{CLK-STB}	CLK \uparrow \rightarrow STB \uparrow	4			ns
STB-CLK Time	t _{STB-CLK}	STB \uparrow \rightarrow CLK \uparrow	4			ns
Time between STB and Start Pulse	t _{STB-STH}	STB \uparrow \rightarrow STHR (STHL) \uparrow	2			CLK
POL-STB Time	t _{POL-STB}	POL \uparrow or \downarrow \rightarrow STB \uparrow	-5			ns
STB-POL Time	t _{STB-POL}	STB \downarrow \rightarrow POL \downarrow or \uparrow	4			ns

Remark Unless otherwise specified, the input level is defined to be $V_{IH} = 0.7 V_{DD1}$, $V_{IL} = 0.3 V_{DD1}$.

Switching Characteristics Waveform

Unless otherwise specified, the input level is defined to be $V_{IH} = 0.7 V_{DD1}$, $V_{IL} = 0.3 V_{DD1}$.



10. RECOMMENDED SOLDERING CONDITIONS

The following conditions must be met for soldering conditions of the μ PD16716.

For more details, refer to the **Semiconductor Device Mounting Technology Manual (C10535E)**.

Please consult with our sales offices in case other soldering process is used, or in case the soldering is done under different conditions.

μ PD16716N-xxx : TCP (TAB package)

Mounting Condition	Mounting Method	Condition
Thermocompression	Soldering	Heating tool 300 to 350°C: heating for 2 to 3 seconds: pressure 100g (per solder)
	ACF (Adhesive Conductive Film)	Temporary bonding 70 to 100°C: pressure 3 to 8 kg/cm ² : time 3 to 5 seconds. Real bonding 165 to 180°C: pressure 25 to 45 kg/cm ² : time 30 to 40 seconds. (When using the anisotropy conductive film SUMIZAC1003 of Sumitomo Bakelite, Ltd.)

Caution To find out the detailed conditions for packaging the ACF part, please contact the ACF manufacturing company. Be sure to avoid using two or more packaging methods at a time.

[MEMO]

[MEMO]

NOTES FOR CMOS DEVICES**① PRECAUTION AGAINST ESD FOR SEMICONDUCTORS**

Note:

Strong electric field, when exposed to a MOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred. Environmental control must be adequate. When it is dry, humidifier should be used. It is recommended to avoid using insulators that easily build static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work bench and floor should be grounded. The operator should be grounded using wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with semiconductor devices on it.

② HANDLING OF UNUSED INPUT PINS FOR CMOS

Note:

No connection for CMOS device inputs can be cause of malfunction. If no connection is provided to the input pins, it is possible that an internal input level may be generated due to noise, etc., hence causing malfunction. CMOS devices behave differently than Bipolar or NMOS devices. Input levels of CMOS devices must be fixed high or low by using a pull-up or pull-down circuitry. Each unused pin should be connected to V_{DD} or GND with a resistor, if it is considered to have a possibility of being an output pin. All handling related to the unused pins must be judged device by device and related specifications governing the devices.

③ STATUS BEFORE INITIALIZATION OF MOS DEVICES

Note:

Power-on does not necessarily define initial status of MOS device. Production process of MOS does not define the initial operation status of the device. Immediately after the power source is turned ON, the devices with reset function have not yet been initialized. Hence, power-on does not guarantee out-pin levels, I/O settings or contents of registers. Device is not initialized until the reset signal is received. Reset operation must be executed immediately after power-on for devices having reset function.

Reference Documents

NEC Semiconductor Device Reliability / Quality Control System (C10983E)

Quality Grades to NEC's Semiconductor Devices (C11531E)

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